

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KAZUHIRO TSUMURA	09/21/2017
RECEIVING PARTY DATA	
Name:	SII SEMICONDUCTOR CORPORATION
Street Address:	8, NAKASE 1-CHOME, MIHAMA-KU
City:	CHIBA-SHI, CHIBA
State/Country:	JAPAN
Postal Code:	261-8507
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15713926
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	BRUCE L. ADAMS
SIGNATURE:	/BRUCE L. ADAMS/
DATE SIGNED:	09/25/2017
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, Kazuhiro TSUMURA, residing at c/o SII Semiconductor Corporation, 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, 261-8507, Japan, have invented new and useful improvements in NON-VOLATILE SEMICONDUCTOR MEMORY DEVICE, for which I have prepared an application for Letters Patent of the United States of America;

AND WHEREAS, SII Semiconductor Corporation, a Japanese corporation located and doing business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, 261-8507, Japan, is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor;

NOW, THEREFORE, be it known by all whom it may concern, that for and in consideration of Ten Dollars (\$10.00) and other good and valuable consideration to me in hand paid, the receipt of which is hereby acknowledged, I have assigned, sold and transferred and by these presents do hereby assign, sell and transfer unto the said SII Semiconductor Corporation for the territory of the United States of America, my entire right, title and interest in and to the said invention, and in and to the said application, prepared and executed by me on September 21, 2017, filed September 21, 2017, Application No. 15/713,926, preparatory to obtaining Letters Patent thereon and in and to any and all divisions, reissues and continuations thereof, and in and to any Letters Patent that may be granted thereon; said invention, application and Letters Patent to be held and enjoyed

by the said SII Semiconductor Corporation, its legal representatives and assigns, as fully and entirely as the same would have been held by me had this assignment, sale and transfer not been made.

AND, I hereby covenant and agree that I will at any time upon the request and at the expense of said assignee execute and deliver any and all papers and do all lawful acts that may be necessary or desirable to perfect the title to said invention and to obtain Letters Patent therefor, and I hereby authorize and request the Honorable Commissioner of Patents and Trademarks to issue the said Letters Patent to the said SII Semiconductor Corporation in accordance with this assignment.

Executed this 21st day of September, 2017.

Witness:

K. Tsumura (L.S.)
Kazuhiro TSUMURA